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December 2015



FSB70325

Motion SPM® 7 Series

Features

- UL Certified No. E209204 (UL1557)
- · High Performance PQFN Package
- 250 V $R_{DS(on)}$ = 1.4 $\Omega(Max)$ FRFET MOSFET 3-Phase Inverter with Gate Drivers and Protection
- Separate Open-Source Pins from Low-Side MOSFETs for Three-Phase Current-Sensing
- Active-HIGH Interface, Works with 3.3 / 5 V Logic, Schmitt-trigger Input
- · Optimized for Low Electromagnetic Interference
- HVIC Temperature-Sensing Built-In for Temperature Monitoring
- HVIC for Gate Driving with Under-Voltage Protection and Interlock Function
- Isolation Rating: 1500 V_{rms} / min.
- Moisture Sensitive Level (MSL) 3
- RoHS Compliant

Application

 3-Phase Inverter Driver for Small Power AC Motor Drives

Related Source

- AN-9077 Motion SPM® 7 Series User's Guide
- AN-9078 Surface Mount Guidelines for Motion SPM® 7 Series

General Description

The FSB70325 is an advanced Motion SPM® 7 module providing a fully-featured, high-performance inverter output stage for AC Induction, BLDC and PMSM motors. These modules integrate optimized gate drive of the built-in MOSFETs (FRFET® technology) to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockouts, thermal monitoring, fault reporting and interlock function. The built-in one HVIC translates the incoming logic-level gate inputs to the high-voltage, high-current drive signals required to properly drive the module's internal MOSFETs. Separate open-souce MOSFET terminals are available for each phase to support the widest variety of control algorithms.



3D Package Drawing (Click to Activate 3D Content)

Package Marking & Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity	
FSB70325	FSB70325	PQFN27A	13"	24 mm	1000 units	

Absolute Maximum Ratings

Inverter Part (each MOSFET unless otherwise specified.)

Symbol	Parameter	Conditions	Rating	Unit
V _{DSS}	Drain-Source Voltage of Each MOSFET		250	V
*I _{D 25}	Each MOSFET Drain Current, Continuous	T _{CB} = 25°C (1st Notes 1)	4.1	Α
*I _{D 80}	Each MOSFET Drain Current, Continuous	$T_{CB} = 80^{\circ}C$	3.1	Α
*I _{DP}	Each MOSFET Drain Current, Peak	T _{CB} = 25°C, PW < 100 μs	8.2	А
*P _D	Maximum Power Dissipation	T _{CB} = 25°C, For Each MOSFET	49	W

Control Part (each HVIC unless otherwise specified.)

Symbol	Parameter	Conditions	Rating	Unit
V _{DD}	Control Supply Voltage	Applied Between V _{DD} and COM	20	V
V _{BS}	High-side Bias Voltage	Applied Between V _B and V _S	20	V
V _{IN}	Input Signal Voltage	Applied Between IN and COM	-0.3 ~ V _{DD} + 0.3	V
V _{FO}	Fault Output Supply Voltage	Applied Between FO and COM	-0.3 ~ V _{DD} + 0.3	V
I _{FO}	Fault Output Current	Sink Current FO Pin	5	mA
V _{CSC}	Current Sensing Input Voltage	Applied Between Csc and COM	-0.3 ~ V _{DD} + 0.3	V

Total System

Symbol	Parameter	Conditions	Rating	Unit
T _J	Operating Junction Temperature		-40 ~ 150	°C
T _{STG}	Storage Temperature		-40 ~ 125	°C
V _{ISO}	Isolation Voltage	60 Hz, Sinusoidal, 1 Minute, Connection Pins to Heat Sink Plate	1500	V _{rms}

1st Notes:

- 1. $T_{\mbox{\footnotesize{CB}}}$ is pad temperature of case bottom.
- 2. Marking " * " is calculation value or design factor.

Pin descriptions

Pin Number	Pin Name	Pin Description
1	/FO	Fault Output
2	V _{TS}	Voltage Output of HVIC Temperature
3	Cfod	Capacitor for Duration of Fault Output
4	Csc	Capacitor (Low-pass Filter) for Short-circuit Current Detection Input
5	V _{DD}	Supply Bias Voltage for IC and MOSFETs Driving
6	IN_UH	Signal Input for High-side U Phase
7	IN_VH	Signal Input for High-side V Phase
8 (8a)	СОМ	Common Supply Ground
9	IN_WH	Signal Input for High-side W Phase
10	IN_UL	Signal Input for Low-side U Phase
11	IN_VL	Signal Input for Low-side V Phase
12	IN_WL	Signal Input for Low-side W Phase
13	Nu	Negative DC-Link Input for U Phase
14	U	Output for U Phase
15	Nv	Negative DC-Link Input for V Phase
16	V	Output for V Phase
17	W	Output for W Phase
18	Nw	Negative DC-Link Input for W Phase
19	V _{S(W)}	High-side Bias Voltage Ground for W phase Mosfet driving
20	P _W	Positive DC-Link Input for W Phase
21	P _V	Positive DC-Link Input for V Phase
22	P _U	Positive DC-Link Input for U Phase
23 (23a)	V _{S(V)}	High-side Bias Voltage Ground for V phase Mosfet driving
24 (24a)	V _{S(U)}	High-side Bias Voltage Ground for U phase Mosfet driving
25	V _{B(U)}	High-side Bias Voltage for U phase Mosfet driving
26	V _{B(V)}	High-side Bias Voltage for V phase Mosfet driving
27	V _{B(W)}	High-side Bias Voltage for W phase Mosfet driving

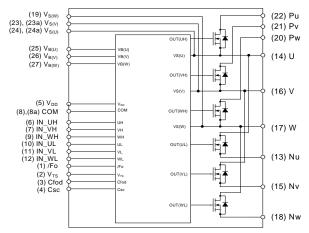


Figure 1. Pin Configuration and Internal Block Diagram

1st Notes

- Source terminal of each low-side MOSFET is not connected to supply ground or bias voltage ground inside Motion SPM® 7 product. External connections should be made as indicated in Figure 2.
- 5. The suffix -a pad is connected with same number pin. ex) 8 and 8a is connected inside.

Electrical Characteristics ($T_J = 25$ °C, $V_{DD} = V_{BS} = 15$ V unless otherwise specified.)

Inverter Part (each MOSFET unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
BV _{DSS}	Drain - Source Breakdown Voltage	V _{IN} = 0 V, I _D = 1 mA (2nd Notes 1)	250	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{IN} = 0 V, V _{DS} = 250 V	-	-	1	mA
R _{DS(on)}	Static Drain - Source Turn-On Resistance	V _{DD} = V _{BS} = 15 V, V _{IN} = 5 V, I _D = 1.0 A	-	1.1	1.4	Ω
V _{SD}	Drain - Source Diode Forward Voltage	$V_{DD} = V_{BS} = 15V$, $V_{IN} = 0$ V, $I_{D} = -1.0$ A	-	0.9	1.2	V
t _{ON}			-	460	-	ns
t _{D(ON)}			-	405	-	ns
t _{OFF}		V _{PN} = 150 V, V _{DD} = V _{RS} = 15 V, I _D = 1.0 A	-	340	-	ns
t _{D(OFF)}	Switching Times	$V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$, Inductive Load L = 3 mH	-	280	-	ns
I _{rr}	Switching Times	Low-Side MOSFET Switching	-	1.3	-	Α
t _{rr}		(2nd Notes 2)	-	72	-	ns
E _{ON}			-	25	-	μJ
E _{OFF}			-	22	-	μJ

Control Part (each HVIC unless otherwise specified.)

Symbol	Parameter	Conditi	Conditions		Тур	Max	Units
I _{QDD}	Quiescent V _{DD} Current	V _{DD} =15V, V _{IN} =0V	V _{DD} - COM	1	1.7	3.0	mA
I _{QBS}	Quiescent V _{BS} Current	V _{BS} =15V, V _{IN} =0V	$\begin{vmatrix} V_{B(X)} \text{-} V_{S(X)}, V_{B(V)} \text{-} V_{S(V)}, \\ V_{B(W)} \text{-} V_{S(W)} \end{vmatrix}$	i	45	70	μΑ
I _{PDD}	Operating V _{DD} Current	V _{DD} =15V,F _{PWM} =20kHz, duty=50%, PWM signal input for Low side	V _{DD} - COM	-	1.9	3.2	mA
I _{PBS}	Operating V _{BS} Current	V _{BS} =15V,F _{PWM} =20kHz, duty=50%, PWM signal input for High side	$\begin{matrix} V_{B(U)}\text{-}V_{S(U)}, V_{B(V)}\text{-}V_{S(V)}, \\ V_{B(W)}\text{-}V_{S(W)} \end{matrix}$	-	300	400	μА
UV _{DDD}	Low-side Undervoltage	V _{DD} Undervoltage Protection	V _{DD} Undervoltage Protection Detection Level		8.0	9.4	V
UV _{DDR}	Protection (Figure 6)	V _{DD} Undervoltage Protection Reset Level		8.0	8.9	9.8	V
UV _{BSD}	High-side Undervoltage	V _{BS} Undervoltage Protection	Detection Level	7.4	8.0	9.4	V
UV _{BSR}	Protection (Figure 7)	V _{BS} Undervoltage Protection	Reset Level	8.0	8.9	9.8	V
V _{TS}	HVIC Temperature sensing voltage output	V _{DD} =15V, T _{HVIC} =25°C (2nd	V _{DD} =15V, T _{HVIC} =25°C (2nd Notes 3) Logic High Level		675	770	mV
V _{IH}	ON Threshold Voltage	Logic High Level			-	2.4	V
V _{IL}	OFF Threshold Voltage	Logic Low Level		0.8	-	-	V
V _{SC(ref)}	SC Current Trip Level	V _{DD} =15V	C _{SC} - COM	0.45	0.5	0.55	V
t _{FOD}	Fault-out Pulse Width	C _{FOD} =33nF (2nd Notes 4)		1.0	1.4	1.8	ms

2nd Notes:

^{1.} BV_{DSS} is the absolute maximum voltage rating between drain and source terminal of each MOSFET inside Motion SPM[®] 7 product. V_{PN} should be sufficiently less than this value considering the effect of the stray inductance so that V_{PN} should not exceed BV_{DSS} in any case.

^{2.} t_{ON} and t_{OFF} include the propagation delay of the internal drive IC. Listed values are measured at the laboratory test condition, and they can be different according to the field applications due to the effect of different printed circuit boards and wirings. Please see Figure 3 for the switching time definition with the switching test circuit of Figure 4.

^{3.} V_{TS} is only for sensing-temperature of module and cannot shutdown MOSFETs automatically.

^{4.} The fault-out pulse width t_{FOD} depends on the capacitance value of C_{FOD} according to the following approximate equation : $C_{FOD} = 24 \times 10^{-6} \times t_{FOD}$ [F]

Recommended Operating Condition

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _{PN}	Supply Voltage	Applied Between P and N	-	150	200	V
V _{DD}	Control Supply Voltage	Applied Between V _{DD} and COM	13.5	15.0	16.5	V
V_{BS}	High-Side Bias Voltage	Applied Between V_B and V_S	13.5	15.0	16.5	٧
dV _{DD} /dt, dV _{BS} /dt	Control Supply Variation		-1.0	-	1.0	V/μs
t _{dead}	Blanking Time for Preventing Arm-Short	$V_{DD} = V_{BS} = 13.5 \sim 16.5 \text{ V}, T_{J} \le 150 ^{\circ}\text{C}$	500	-	-	ns
f _{PWM}	PWM Switching Frequency	$T_{J} \le 150^{\circ}C$	-	15	-	kHz

Thermal Resistance

•,	Symbol	Parameter		Conditions	Min.	Тур.	Max.	Unit
	$R_{\theta JCB}$	Junction to Case E Thermal Resistance	Bottom	Single MOSFET Operating Condition (3rd Notes 1)	-	2.0	-	°C/W

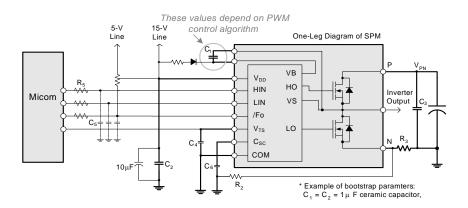


Figure 2. Recommended MCU Interface and Bootstrap Circuit with Parameters

3rd Notes

- 1. $R_{\theta JCB}$ is simulation value with application board layout. (Please refer user's guide SPM7 series)
- 2. Parameters for bootsrap circuit elements are dependent on PWM algorithm. For 15 kHz of switching frequency, typical example of parameters is shown above.
- 3. RC coupling(R₅ and C₅) at each input (indicated as dotted lines) may be used to prevent improper input signal due to surge noise. Signal input of SPM[®] is compatible with standard CMOS or LSTTL outptus.
- 4. Bold lines should be short and thick in PCB pattern to have small stray inductance of circuit, which results in the reduction of surge voltage.

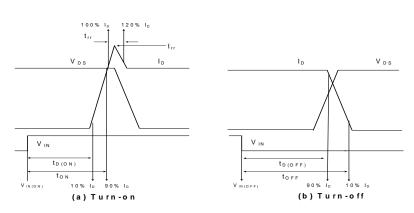


Figure 3. Switching Time Definition

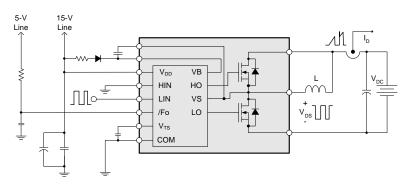


Figure 4. Switching Test Circuit (Low-side)

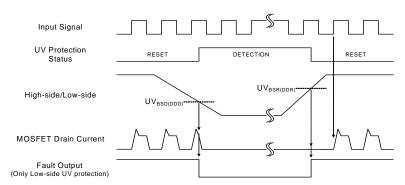


Figure 5. Under Voltage Protection

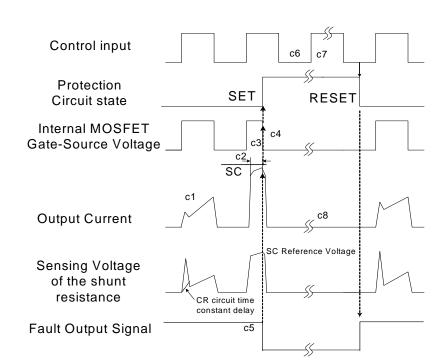


Figure 6. Short-Circuit Current Protection

(with the external shunt resistance and CR connection)

c1: Normal operation: MOSFET ON and carrying current.

c2 : Short circuit current detection (SC trigger).

c3: Hard MOSFET gate interrupt.

c4: MOSFET turns OFF.

c5 : Fault output timer operation start : Fault-out width $(t_{\mbox{FOD}})$

c6: Input "L": MOSFET OFF state.

c7: Input "H": MOSFET ON state, but during the active period of fault output the MOSFET doesn't turn ON.

c8: MOSFET OFF state

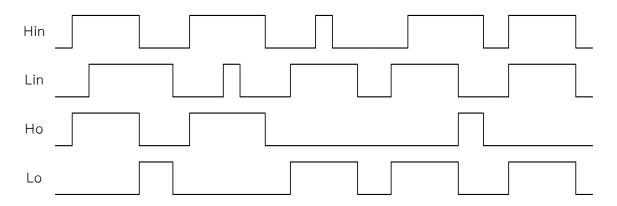


Figure 7. Timing Chart of Interlock Function

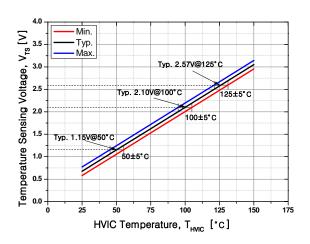


Figure 8. Temperature profile V_{TS} vs. T_{HVIC}

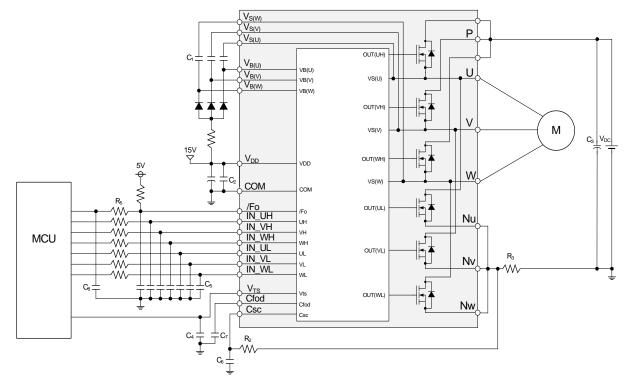
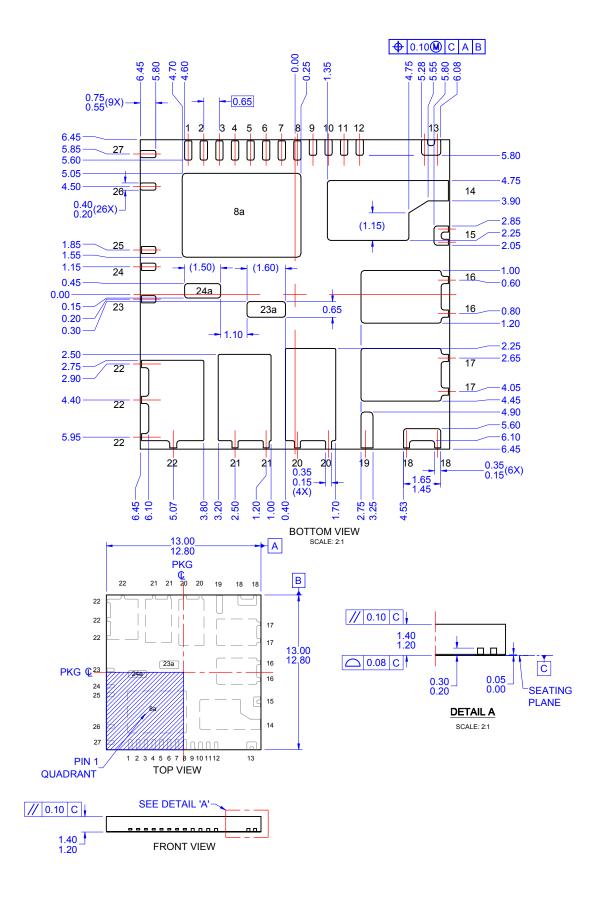
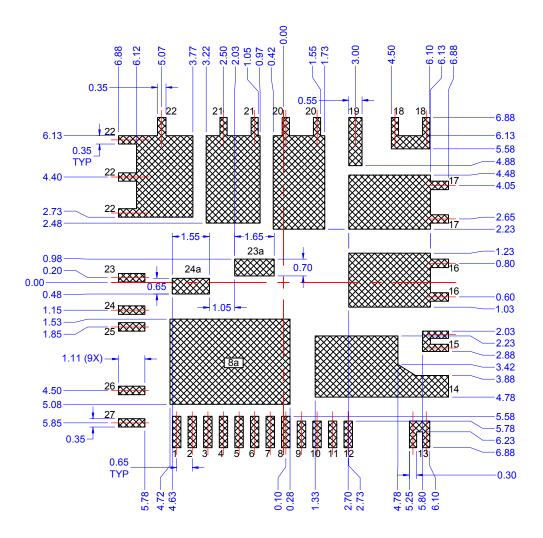


Figure 9. Example of Application Circuit

4th Notes

- 1. RC-coupling (R_5 and C_5 , R_2 and C_6) and C_1 , C_5 , C_7 , C_8 at each input of Motion SPM $^{\otimes}$ 7 product and MCU are useful to prevent improper input signal caused by surge-noise.
- 2. Ground-wires and output terminals, should be thick and short in order to avoid surge-voltage and malfunction of HVIC.
- 3. All the filter capacitors should be connected close to Motion SPM 7 product, and they should have good characteristics for rejecting high-frequency ripple current.





LAND PATTERN RECOMMENDATION SCALE: 2:1

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